

SOT1384-4

WLCSP9, wafer level chip-scale package; 9 bumps; 1.50 mm x 1.28 mm x 0.60 mm body

7 March 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP9
Package type industry code	WLCSP9
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	3-3-2017
Manufacturer package code	SOT1384-4

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.47	-	1.5	1.53	mm
E	package width	1.25	-	1.28	1.31	mm
A	seated height	-	-	-	0.6	mm
A ₂	package height	0.34	-	0.36	0.38	m
e	nominal pitch	-	-	0.4	-	mm



2. Package outline

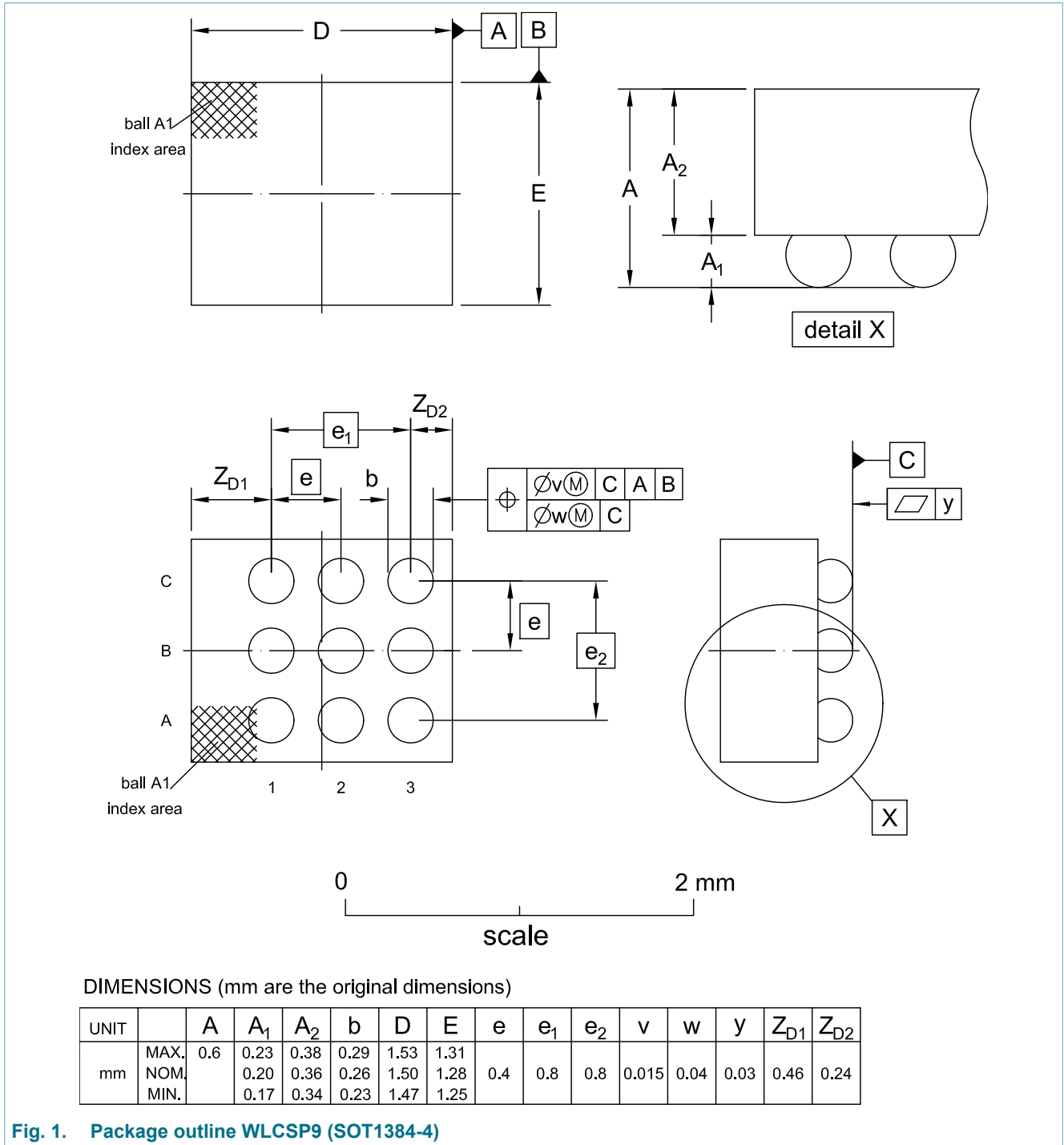


Fig. 1. Package outline WLCSP9 (SOT1384-4)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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Date of release: 7 March 2017
